

STN	Skúšobná metóda pre mechanické vlastnosti flexibilných dosiek s optoelektrickými obvodmi pri tepelnom namáhaní	STN EN IEC 63251 34 6513
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Test method for mechanical properties of flexible opto-electric circuit boards under thermal stress

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 01/24

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EN IEC 63251

NORME EUROPÉENNE

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December 2023

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English Version

Test method for mechanical properties of flexible opto-electric
circuit boards under thermal stress
(IEC 63251:2023)

Méthode d'essai des propriétés mécaniques des circuits
optoélectriques souples sous contrainte thermique
(IEC 63251:2023)

Prüfverfahren für mechanische Eigenschaften von
elektrisch-optischen Leiterplatten unter
Wärmebeanspruchung
(IEC 63251:2023)

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EN IEC 63251:2023 (E)**European foreword**

The text of document 91/1898/FDIS, future edition 1 of IEC 63251, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 63251:2023.

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IEC 60793-2 (series) NOTE Approved as EN 60793-2 (series)

IEC 62496-3-1 NOTE Approved as EN 62496-3-1

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

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NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-2-2	-	Environmental testing - Part 2-2: Tests Test B: Dry heat	-EN 60068-2-2	-
IEC 60068-2-14	-	Environmental testing - Part 2-14: Tests Test N: Change of temperature	-EN IEC 60068-2-14	-
IEC 60068-2-78	-	Environmental testing - Part 2-78: Tests Test Cab: Damp heat, steady state	-EN 60068-2-78	-



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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Test method for mechanical properties of flexible opto-electric circuit boards
under thermal stress**

**Méthode d'essai des propriétés mécaniques des circuits optoélectriques
souples sous contrainte thermique**



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IEC Secretariat
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
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Edition 1.0 2023-11

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Test method for mechanical properties of flexible opto-electric circuit boards
under thermal stress**

**Méthode d'essai des propriétés mécaniques des circuits optoélectriques
souples sous contrainte thermique**

INTERNATIONAL
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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHOD FOR MECHANICAL PROPERTIES OF FLEXIBLE
OPTO-ELECTRIC CIRCUIT BOARDS UNDER THERMAL STRESS**

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The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1898/FDIS	91/1914/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

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TEST METHOD FOR MECHANICAL PROPERTIES OF FLEXIBLE OPTO-ELECTRIC CIRCUIT BOARDS UNDER THERMAL STRESS

1 Scope

This International Standard defines the thermal endurance test methods for reliability assessment of flexible opto-electric circuit boards. The purpose of this document is to accommodate the uniform thermal characteristics required by the flexible opto-electric circuit in high temperature environments such as automobiles. In particular, this document specifies a test method to inspect the occurrence of colour exchange, deformation and delamination of flexible opto-electric circuit boards under thermal stress.

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IEC 60068-2-2, *Environmental testing – Part 2-2: Tests – Test B: Dry heat*

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